PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4037631

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ELEMENT SIX TECHNOLOGIES US CORPORATION	09/02/2016

RECEIVING PARTY DATA

Name:	RFHIC CORPORATION
Street Address:	RFHIC BLDG. 41-14, BURIM-RO 170 BEON-GIL,
Internal Address:	DONGAN-GU, ANYANG-SI, GYEONGGI-DO
City:	ANYANG-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	14055

PROPERTY NUMBERS Total: 7

Property Type	Number
Patent Number:	7595507
Patent Number:	8283672
Patent Number:	8283189
Patent Number:	8945966
Patent Number:	8796843
Patent Number:	8674405
Patent Number:	9359693

CORRESPONDENCE DATA

Fax Number: (408)716-4985

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 4087180512
Email: cspark@cspto.com
Correspondent Name: CHUNG SIK PARK
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NAME OF SUBMITTER:	CHUNG SIK PARK
SIGNATURE:	/Chung.Park/
DATE SIGNED:	09/03/2016

Total Attachments: 4
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CONFIRMATORY ASSIGNMENT

PARTIES:

(1) **ELEMENT SIX TECHNOLOGIES US CORPORATION**, of 3901 Burton Drive, Santa Clara, CA95054, United States of America (the "ASSIGNOR") and

(2) **RFHIC CORPORATION**, a Republic of Korea company headquartered in Anyang-Si, Republic of Korea, with offices in Morrisville, North Carolina, United States of America, (the "ASSIGNEE");

each a "PARTY" and together the "PARTIES".

1. DEFINITIONS:

For the purposes of this Assignment:

1.1 "PATENTS" shall mean, collectively and severally, the patents and patent applications listed in the SCHEDULE to this Assignment.

1.2 "INVENTIONS" shall mean the inventions to which the PATENTS relate.

2. WHEREAS:

2.1 By virtue of an agreement between the PARTIES dated 15th July 2016, (the "AGREEMENT") the ASSIGNOR has assigned to the ASSIGNEE all its right title and interest in and to the INVENTION and the PATENTS.

2.2. For the avoidance of doubt, and so as to confirm ASSIGNEE's legal title to the same, the Parties have agreed to execute this Assignment for the purpose of ensuring that all ASSIGNOR's rights in the INVENTIONS and PATENTS and all other intellectual property rights relating thereto are vested in ASSIGNEE.

3. IT IS AGREED THAT:

In consideration of the sum of $1(one United States Dollar) paid by ASSIGNOR to ASSIGNEE, the receipt of which is hereby acknowledged:

3.1 ASSIGNOR as necessary hereby confirms the assignment of and assigns to ASSIGNEE, and ASSIGNEE as necessary hereby confirms its acceptance of and accepts all ASSIGNOR's property right title and interest in and to the INVENTIONS and PATENTS for all relevant states including without limitation:

(a) the right to apply for and obtain patents in respect of the INVENTIONS in any country in the world;

(b) all right, title and interest in and to the PATENTS and all patent applications, patents and supplementary protection certificates which may now or at any time in the future derive or result or claim priority from the same or otherwise relate to the INVENTIONS, including without limitation any divisionals, continuations, continuations-in-part, reissues, re-examination certificates, post-grant reviews, inter partes reviews, supplemental examinations, extensions, renewals and registrations in relation to any thereof and all and any other rights in the inventions comprised in any of the same (hereinafter collectively and severally "the PATENT RIGHTS");

(c) the benefit of all priority dates;

(d) the right to seek and obtain registrations in any country in the world in respect of any patent deriving from the PATENTS or otherwise included in the PATENT RIGHTS;

(e) the right to sue for and obtain injunctive relief, damages and all other relief in respect of any infringement or misuse (whether past present or future) of any of the PATENT RIGHTS or of the rights conferred by publication of any of the same.

3.2 Each PARTY authorises and requests his/her professional representative before any national or regional patent office to insert an appendix signed and dated by the professional representative detailing the filing date and application number of any patent application, patent and/or supplementary protection certificates which may now or at any time in the future derive or result or claim priority from the PATENTS where needed for effective recordal of any such patent application or patent at any national or regional patent office.

3.3 ASSIGNOR hereby covenants and agrees to and with ASSIGNEE that, at the time of execution and delivery of the AGREEMENT, ASSIGNOR was the sole and lawful owner of the entire right, title, and interest in and to the INVENTIONS and PATENTS, and that ASSIGNOR had good and full right and lawful authority to sell and convey the same.

3.4 ASSIGNOR will, without further consideration, communicate to the ASSIGNEE any facts known to the ASSIGNOR regarding the INVENTION and the PATENTS, sign all lawful papers, execute all oaths, assignments, powers of attorney, applications and any other paper desired by ASSIGNEE to obtain, perfect, or secure to ASSIGNEE any and all of the rights, titles and interests herein conveyed, and to maintain, enforce, and defend these rights, titles and interests in any country in the world. ASSIGNOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE under this clause 3.4.

3.5 At the request and expense of the ASSIGNEE, ASSIGNOR will testify in any legal proceeding to obtain, perfect, or secure to ASSIGNEE any and all of the rights, titles and interests herein conveyed, and to maintain, enforce, and defend these rights, titles and interests in any country in the world. ASSIGNOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE under this clause 3.5

3.6 ASSIGNOR hereby agrees to execute all such documents and do all such things as may be required by the law of any country in order to record the PATENTS and any other PATENT RIGHTS in the name of ASSIGNEE.

3.7 This Assignment shall be governed by the laws of New York, United States of America, and the parties submit to the exclusive jurisdiction of the courts of North Carolina, United States of America in respect of any dispute relating to this Assignment.

Signed on behalf of
ELEMENT SIX TECHNOLOGIES US CORPORATION

Signature: [signature]

Name: Mark Thurlow

Title: Head of Business Dev

Date: 2nd September 2016

Signed on behalf of
RFHIC CORPORATION

Signature: [signature]

Name: Deoksoo Cho

Title: CEO

Date: 31/8/2016

SCHEDULE

E6 Family Reference	Country	Application Number Application Date (Filed-on Date)	Publication Number (Publication Date)	Grant Number (Grant Date)	Parent Application (unless where directly from priority/provisional applications)	Priority/Provisional Application Number (Priority/Provisional Application Date)	Inventor(s)	Official Title	Reference
PF1244	US	11/279553 12-Apr-2006 (12-Apr-2006)	US20060266280 (30-Nov-2006)	US7595507 (29-Sep-2009)		US Provisional Application 60/671411 (13 Apr 2005)	FRANCIS, Daniel; EJECKAM, Felix; WASSERBAUER, John; BABIC, Dubravko	Semiconductor Devices having Gallium Nitride Epilayers on Diamond Substrates	PF1244-US-2
	US	12/484098 12-Apr-2006 (12-Jun-2009)	US20100001293 (07-Jan-2010)	US8283672 (09-Oct-2012)	Continuation of US Application 11/279533				PF1244-US-3
	US	12/569486 12-Apr-2006 (29-Sep-2009)	US20100105166 (29-Apr-2010)	US8283189 (09-Oct-2012)	Division of US Application 11/279533				PF1244-US-4
	US	13/608902 12-Apr-2006 (10-Sep-2012)	US20130183798 (18-Jul-2013)	US8945966 (03-Feb-2015)	Division of US Application 12/569486				PF1244-US-5
PF1246	US	12/855274 12-Aug-2010 (12-Aug-2010)	Not published prior to issue	US8796843 (05-Aug-2014)		US Provisional Application 61/233390 (12-Aug-2009)	BABIC, Dubravko; SCHREIBER, Alex; DIDUCK, Quentin	RF and Millimeter-Wave High-Power Semiconductor Device Packaging	PF1246-US-2
PF1248	US	13/407588 28-Feb-2012 (28-Feb-2012)	Not published prior to issue	US8674405 (18-Mar-2014)	Continuation-in-part of US Application 12/484098	US Provisional Application 61/447569 (28-Feb-2011)	BABIC, Dubravko; NASSER-FAILI, Firooz; FRANCIS, Daniel; DIDUCK, Quentin; EJECKAM, Felix	Gallium-Nitride-on-Diamond Wafers and Devices, and Methods of Manufacture	PF1248-US-2
	US	14/163681 28-Feb-2012 (29-Jan-2014)	US20140141595 (22-May-2014)	US8759134 (24-Jun-2014)	Division of US Application 13/407588				PF1248-US-3
PF1249	EP	13748111.8 02-Jul-2013 (16 Dec 2014)	EP2870626 (13-May-2015)		National phase of International Application PCT/IB2013/055417 filed 02-Jul-2013, published as WO2014006562 on 09-Jan-2014	US Provisional Application 61/667864 (03-Jul-2012)	DIDUCK, Quentin; FRANCIS, Daniel; LOWE, Frank Yantis; EJECKAM, Felix	Handle for Semiconductor-On-Diamond Wafers and Method of Manufacture	PF1249-EPw-0
	JP	2015-519469 02-Jul-2013 (26 Dec 2014)	JP2015-523213 (03-Aug-2015)						PF1249-JPw-0
	US	14/409867 02-Jul-2013 (19 Dec 2014)	US20150200254 (16-Jul-2015)						PF1249-USw-0
PF1250	EP	13754987.9 28-Feb-2013 (22 Aug 2014)	EP2820173 (07Jan-2015)		National phase of International Application PCT/US2013/028406 filed 28-Feb-2013, published as WO2013130873 on 06-Sep-2013	US Provisional Application 61/604979 (29-Feb-2012)	FRANCIS, Daniel; NASSER-FAILI, Firooz; MATTHEWS, Kristopher; LOWE, Frank Yantis; DIDUCK, Quentin; ZAYTSEV, Sergey EJECKAM, Felix	Gallium-Nitride-on-Diamond Wafers, Manufacturing Equipment, and Methods of Manufacture	PF1250-EPw-0
	JP	2014-560054 28-Feb-2013 (29 Aug 2014)	JP2015509479 (30-Mar-2015)						PF1250-JPw-0
	JP	2015-209822 28-Feb-2013 (26 Oct 2015)	JP2016064979 (28-Apr-2016)		Division of JP application 2014-560054				PF1250-JP-2
	US	13/781054 28-Feb-2013 (28 Feb 2013)	US20130298823 (14-Nov-2013)	US9359693 (07-Jun-2016)					PF1250-US-2

E6 Family Reference	Country	Application Number Application Date (Filed-on Date)	Publication Number (Publication Date)	Grant Number (Grant Date)	Parent Application (unless where directly from priority/provisional applications)	Priority/Provisional Application Number (Priority/Provisional Application Date)	Inventor(s)	Official Title	Reference
PF1252	CN	201380055651.4 25-Oct-2013 (24 Apr 2015)	CN104756245 (01-Jul-2015)		National phase of International Application PCT/US2013/066778 filed 25-Oct-2013, published as WO 201-4066740 on 01-May-2014	US Provisional Application 61/719201 (26-Oct-2012)	FRANCIS, Daniel; BABIC, Dubravko; NASSER-FAILI, Firooz; EJECKAM, Felix DIDUCK, Quentin; SMART, Joseph; MATTHEWS, Kristopher; LOWE, Frank Yantis	Method for Manufacturing Electronic Devices with Improved Reliability	PF1252-CNw-0
	EP	13793010.3 25-Oct-2013 (13-Mar-2015)	EP2912685 (02 Sep-2015)						PF1252-EPw-0
	JP	2015-539829 25-Oct-2013 (24-Apr-2015)	JP2015533774 (26-Nov-2015)						PF1252-JPw-0
	US	14/432721 25-Oct-2013 (31-Mar 2015)	US20150279945 (01 Oct 2015)						PF1252-USw-0
PF1264	GB	1415353.6 29-Aug-2014 (29 Aug 2014)	GB2518752 (01-Apr-2015)			US Provisional Application 61/872803 (02-Sep-2013) GB Priority Application 1319117.6 (30-Oct-2013)	NASSER-FAILI, Firooz	Semiconductor Device Structures Comprising Polycrystalline CVD Diamond with Improved Near-Substrate Thermal Conductivity	PF1264-GB-2
	EP	14762205.4 29-Aug-2014 (22 Jan 2016)	EP3042389 (13-Jul-2016)		National phase of International Application PCT/US2014/053544 filed 29-Aug-2014, published as WO2015031833 on 05-Mar-2015				PF1264-EPw-0
	JP	2016-540296 29-Aug-2014 (02 Mar 2016)							PF1264-JPw-0
	US	14/909791 29-Aug-2014 (03 Feb 2016)	US20160197027 (07-Jul-2016)						PF1264-USw-0